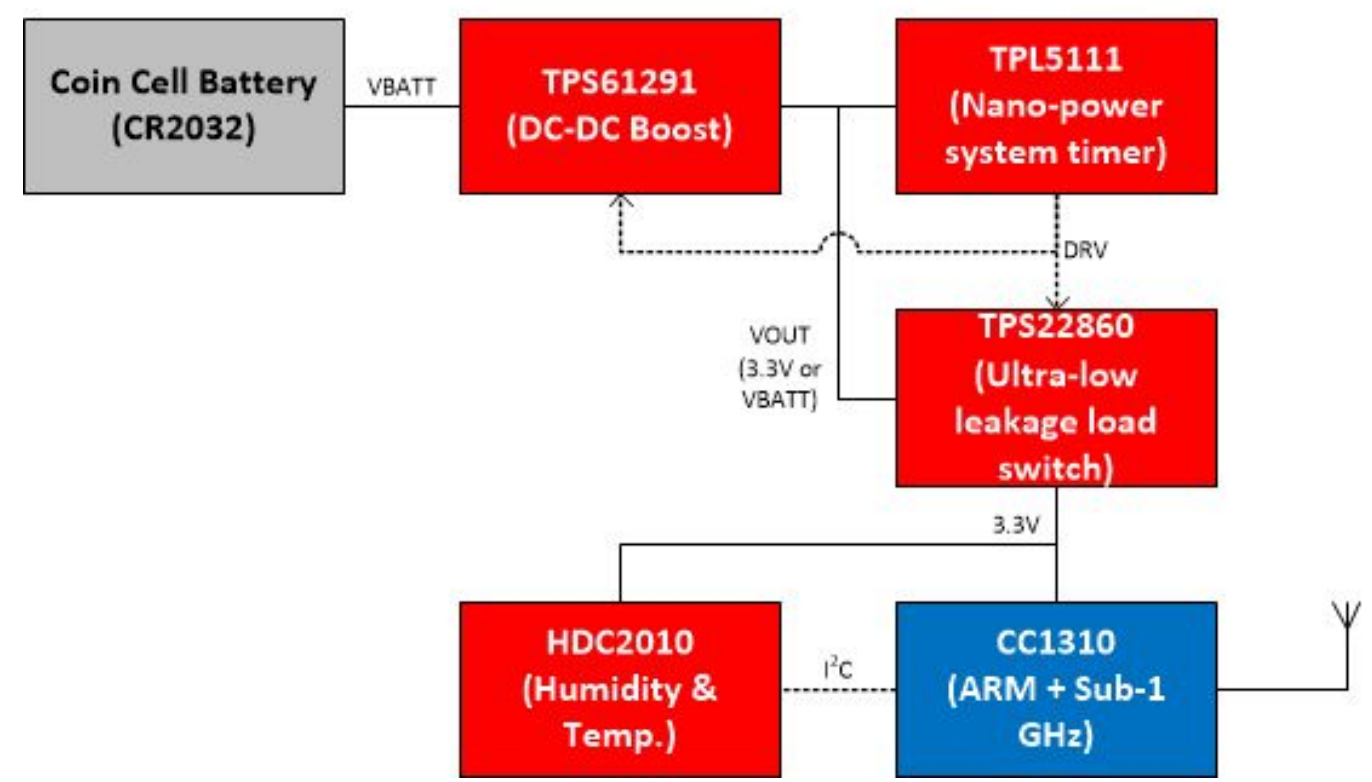
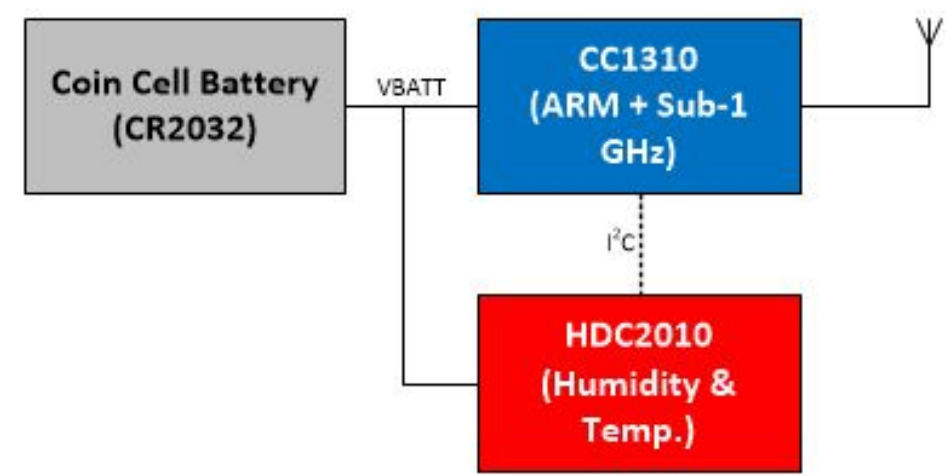


Revision History	
Revision	Notes
A	Initial Board Release
B	Updated wireless MCU passive part numbers.

Nano-Timer Power Cycled Implementation



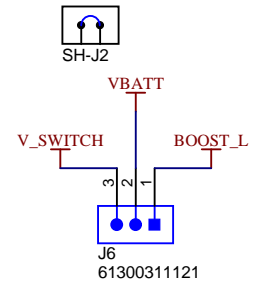
Sensor-to-Cloud Implementation



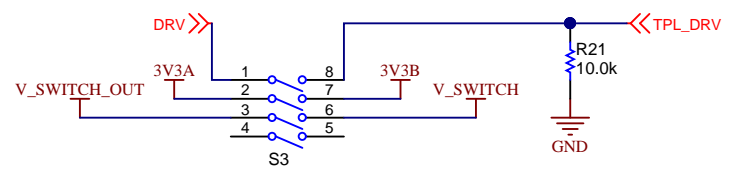
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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/7/2018	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2018
TID #: TIDA-01477	Project Title: Humidity & Temperature Sensing Node for Sub-1 GHz		
Number: TIDA-01477	Rev: B	Sheet Title: CoverSheet	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4	
Drawn By: Evan Cornell	File: TIDA-01477_CoverSheet_SchDoc	Size: B	
Engineer: Jarrod Krebs	Contact: http://www.ti.com/support		

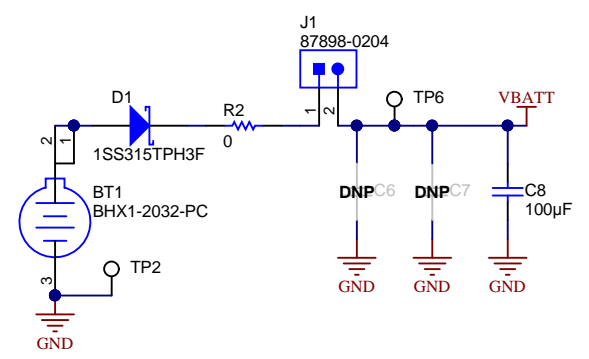
A



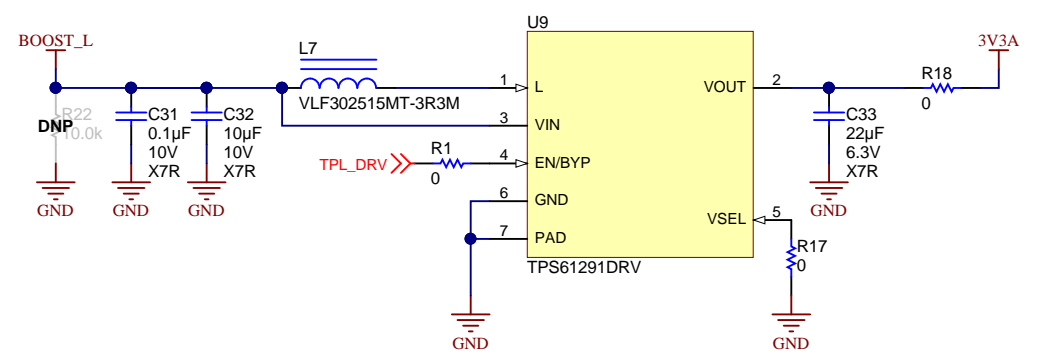
Enable TIDA-00484 Functionality



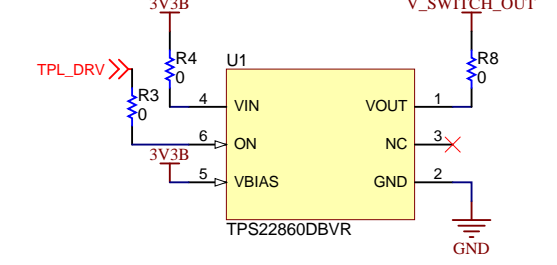
Battery Connector & Reservoir Capacitors



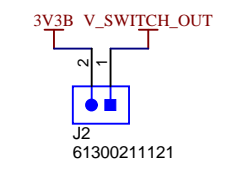
Boost DC-DC to 3.3V



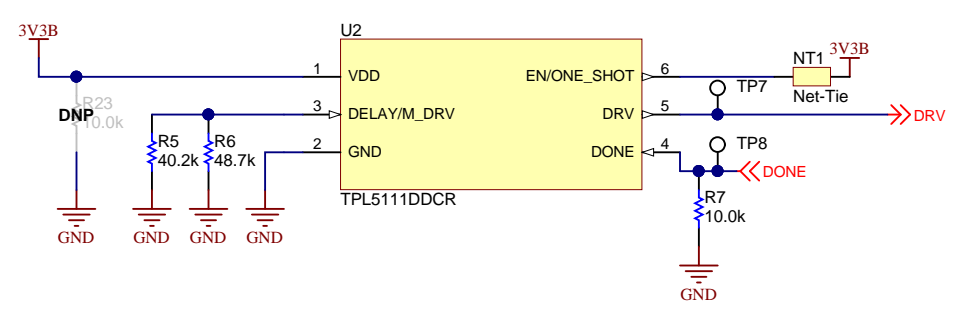
Analog Switch for Power Shutoff



Bypass Jumper for Debugging



Nano-Power System Timer



B

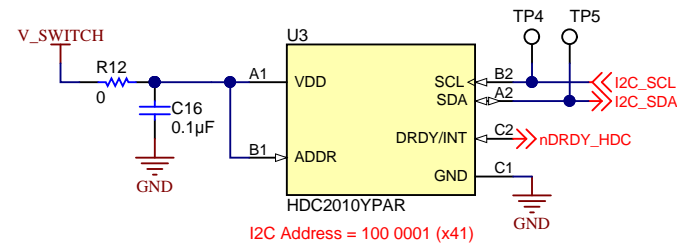
C

D

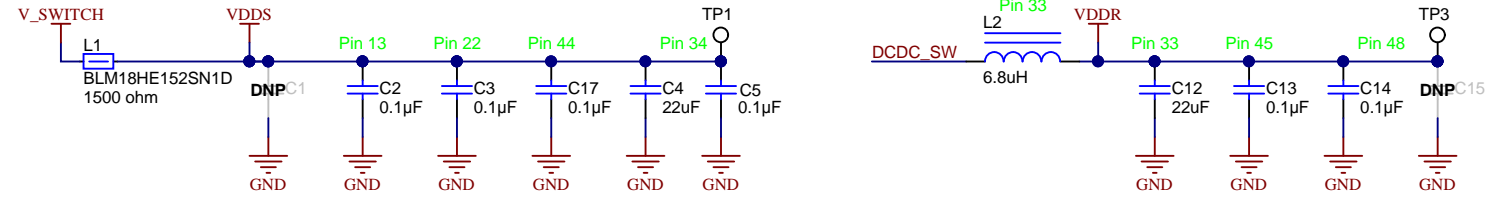
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TID #: TIDA-01477	Project Title: Humidity & Temperature Sensing Node for Sub-1 G	Sheet Title: Power	
Number: TIDA-01477	Rev: B	Assembly Variant: 001	
SVN Rev: Version control disabled	File: TIDA-01477_Power.SchDoc	Sheet: 2 of 4	
Drawn By: Evan Cornell	Engineer: Jarrod Krebs	Contact: http://www.ti.com/support	

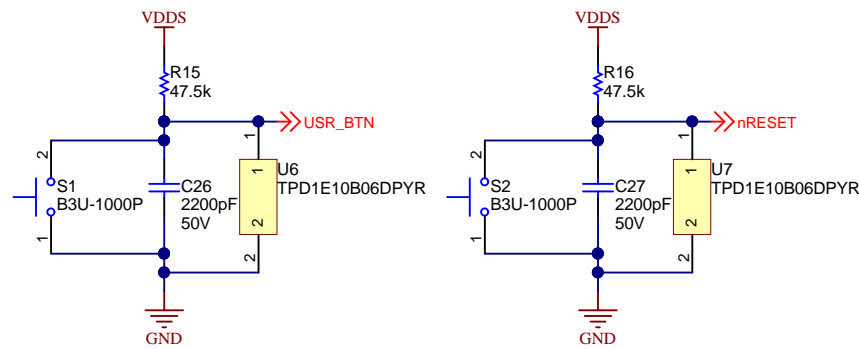
Humidity to Digital Converter



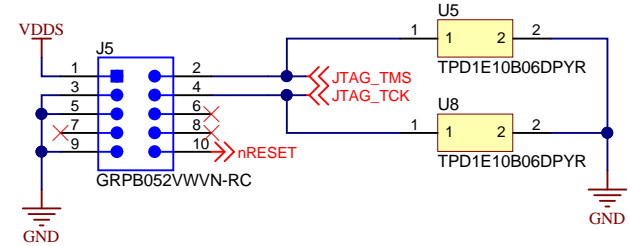
LPRF Bypass Capacitors & DC-DC Passives



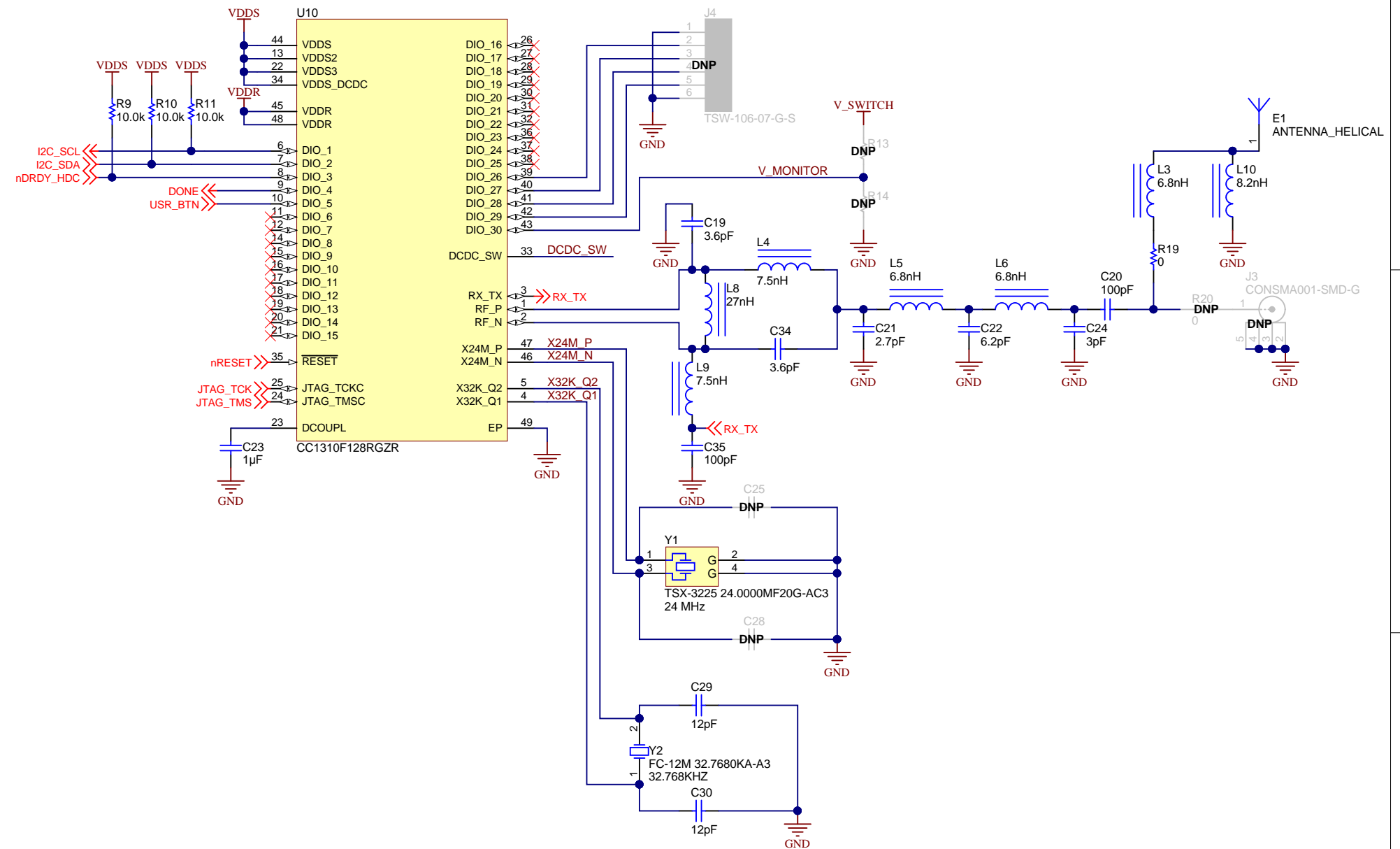
User and Reset Switches



JTAG Programming Interface



Wireless MCU



Orderable: N/A	Designed for: Public Release	Mod. Date: 9/11/2018
TID #: TIDA-01477	Project Title: Humidity & Temperature Sensing Node for Sub-1 G	
Number: TIDA-01477	Rev: B	Sheet Title: MCU_HDC
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By: Evan Cornell	File: TIDA-01477_MCU_HDC.SchDoc	Size: B
Engineer: Jarrod Krebs	Contact: http://www.ti.com/support	

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3 DNP FID4 DNP FID5 DNP FID6

PCB Number: TIDA-01477
PCB Rev: B



PCB LOGO
FCC disclaimer

PCB LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	Default Build

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 10/10/2017	
TID #: TIDA-01477	Project Title: Humidity & Temperature Sensing Node for Sub-1 G		
Number: TIDA-01477	Rev: B	Sheet Title: Hardware	http://www.ti.com © Texas Instruments 2018
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4	
Drawn By: Evan Cornell	File: TIDA-01477_TID_Hardware.SchDoc	Size: B	
Engineer: Jarrod Krebs	Contact: http://www.ti.com/support		

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